

Title (en)  
VACUUM PACKAGE FABRICATION OF MICROELECTROMECHANICAL SYSTEM DEVICES WITH INTEGRATED CIRCUIT COMPONENTS

Title (de)  
VACUUMGEHÄUSEHERSTELLUNG MIKROMECHANISCHER SYSTEME MIT INTEGRIERTEN TEILEN

Title (fr)  
FABRICATION AVEC ENCAPSULATION SOUS VIDE DE DISPOSITIFS DE SYSTEME MECANIQUE MICROELECTRIQUE COMPRENANT DES COMPOSANTS DE CIRCUITS INTEGRES

Publication  
**EP 1272422 A2 20030108 (EN)**

Application  
**EP 01906897 A 20010201**

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Abstract (en)  
[origin: WO0156921A2] A method for vacuum packaging MEMS devices is provided that comprises forming a plurality of MEMS devices (12) on a device wafer (10). A first sealing ring (16) is formed surrounding one of the MEMS devices (12) and any associated mating pads (70). A plurality of integrated circuit devices (80) is formed on a lid wafer (30) where each integrated circuit device (80) has one or more associated mating pads (82) and one or more associated bonding pads (86). A plurality of second sealing rings (32) is formed on the lid wafer (30) where each of the second sealing rings (32) surrounds one of the integrated circuit devices (80) and any associated bonding pads (82). The second sealing ring (32) is positioned between the perimeter of the integrated circuit device (80) and the associated bonding pads (86). A sealing layer is formed on either each first sealing ring (16) or each second sealing ring (32). The device wafer (10) is mated with the lid wafer (30) in a vacuum environment to form a plurality of vacuum packages where each vacuum package encloses one or more of the MEMS devices (12) and one or more of the integrated circuit devices (80).

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